

CRMKGH1006A

N-Channel 100V, 7.1mΩ Typ. Power MOSFET

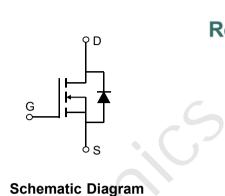
Description

Features

• 100V, 88A

 $R_{DS(ON)}$ Typ = 7.1m Ω @ V_{GS} = 10V

- Advanced Split Gate Trench Technology
- Excellent R_{DS(ON)} and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔVds TESTED!



G S G D S

Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMKGH1006A	CRMKGH1006A	TO-252-3L	TAPING	13"	2500	25000

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
V _{DS}	Drain-to-Source Voltage		100	V
V _{GS}	Gate-to-Source Voltage		±20	V
Ι _D	Continuous Drain Current	T _C = 25°C	88	А
		T _C = 100°C	52.8	А
I _{DM}	Pulsed Drain Current ⁽¹⁾		352	А
E _{AS}	Single Pulsed Avalanche Energy ⁽²⁾		144	mJ
P _D	Power Dissipation	T _C = 25°C	125	W
$R_{ extsf{ heta}JC}$	Thermal Resistance, Junction to Case		1	°C/W
Τ _J , Τ _{stg}	Junction & Storage Temperature Range		-55 to 150	°C



Application

- PWM Application
- Power Management



Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Char	acteristics					
V _{(BR)DSS}	Drain-Source Breakdown Voltage	$I_{\rm D}$ = 250 μ A, $V_{\rm GS}$ = 0V	100	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 100V, V _{GS} = 0V	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics				6	
V _{GS(th)}	Gate Threshold Voltage	V_{DS} = V_{GS} , I_D = 250 μ A	2.4	3	3.6	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = 10V, I _D = 30A	-	7.1	9.3	mΩ
Dynamic	Characteristics					
C _{iss}	Input Capacitance		-	1772	-	pF
C _{oss}	Output Capacitance	V _{GS} = 0V, V _{DS} = 50V, f = 1MHz	-	950	-	pF
C _{rss}	Reverse Transfer Capacitance		Χ-	18	-	pF
Q _g	Total Gate Charge	(_	29	-	nC
Q_gs	Gate Source Charge	$V_{GS} = 0$ to 10V $V_{DS} = 50V$, $I_{D} = 20A$	9.	6.8	-	nC
Q_gd	Gate Drain("Miller") Charge	$v_{\rm DS} = 50 v, I_{\rm D} = 20 A$	-	8.4	-	nC
Switchin	g Characteristics					
t _{d(on)}	Turn-On DelayTime		-	8.4	-	ns
t _r	Turn-On Rise Time	V _{GS} = 10V, V _{DD} = 50V	-	9.4	-	ns
$t_{d(off)}$	Turn-Off DelayTime	I_D = 20A, R_{GEN} = 6 Ω	-	27	-	ns
t _f	Turn-Off Fall Time		-	18	-	ns
Drain-So	urce Diode Characteristics and M	lax Ratings				
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	88	А
I _{SM}	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	352	А
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = 30A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time		-	45	-	ns
Qrr	Body Diode Reverse Recovery Charge	I _F = 15A, di/dt = 100A/us	-	53	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2. E_{AS} condition: Starting T_J=25°C, V_{DD}=50V, V_G=10V, R_G=250hm, L=0.5mH, I_{AS}=24A

3. Pulse Test: Pulse Width \leqslant 300µs, Duty Cycle \leqslant 0.5%.



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Test Circuit

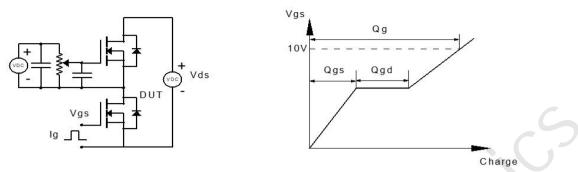


Figure 1: Gate Charge Test Circuit & Waveform

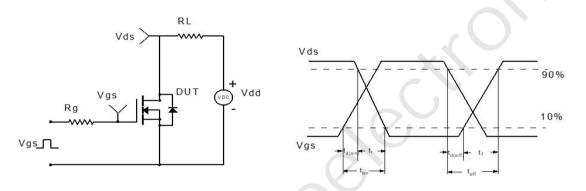
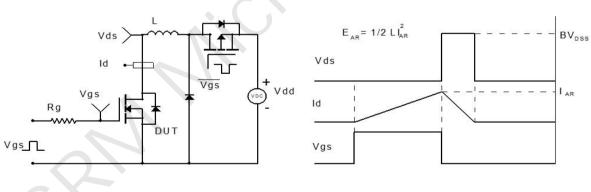


Figure 2: Resistive Switching Test Circuit & Waveform





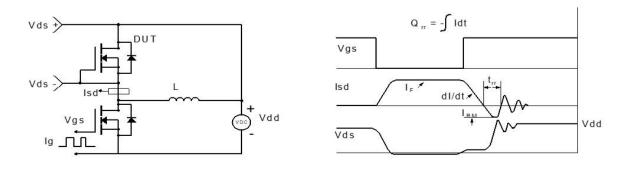
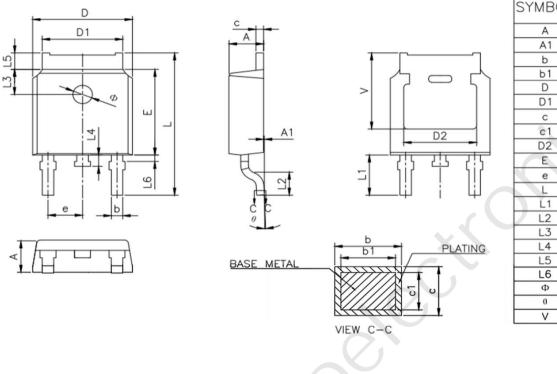


Figure 4: Diode Recovery Test Circuit & Waveform



Package Mechanical Data(TO-252-3L)



SYMBOL	MILLIMETER				
STMDUL	MIN	NOM	MAX		
A	2.20	2.30	2.40		
A1	0.00		0.127		
b	0.66		0.86		
b1	0.65	0.76	0.81		
D	6.50	6.60	6.70		
D1	5.10	5.33	5.46		
с	0.47		0.60		
c1	0.46	0.51	0.56		
D2	4.83 REF.				
E	6.00	6.10	6.20		
е	2.186	2.286	2.386		
L	9.80	10.10	10.40		
L1	2.90 REF.				
L2	1.40	1.50	1.60		
L3	1.80 REF.				
L4	0.60	0.80	1.00		
L5	0.90		1.25		
L6	0.15		0.75		
Φ	1.10		1.30		
θ	0.		8'		
V	5.40 REF				

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